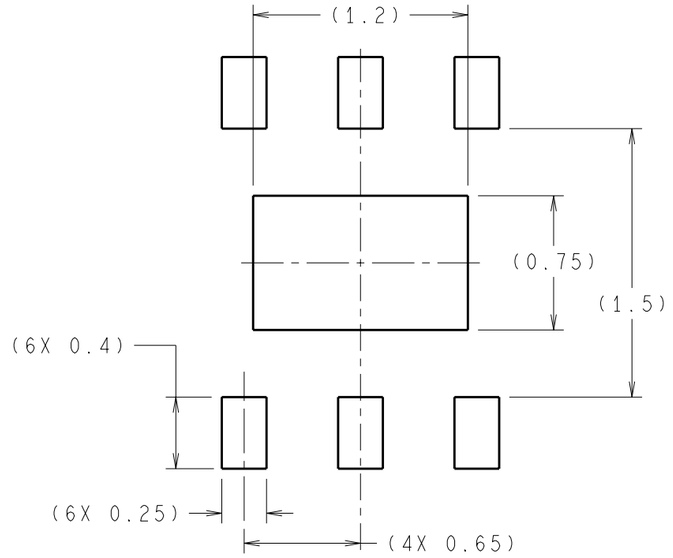
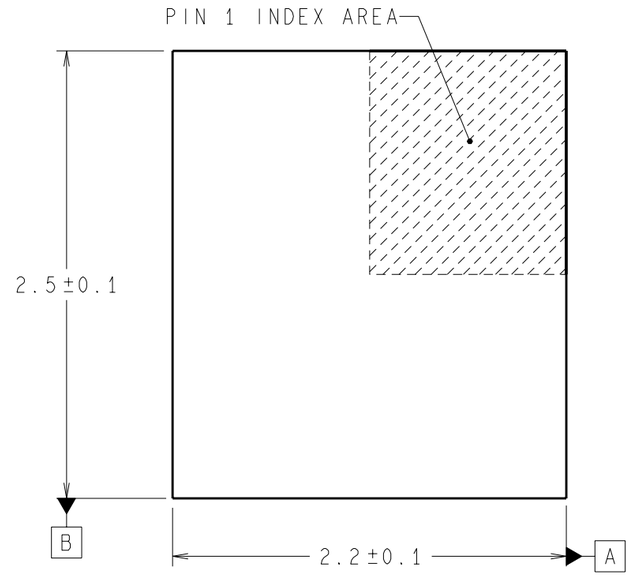
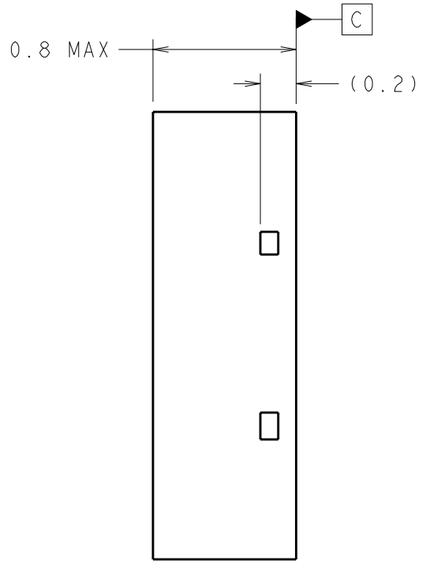
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	564	03/21/2002	AS/MS/SN

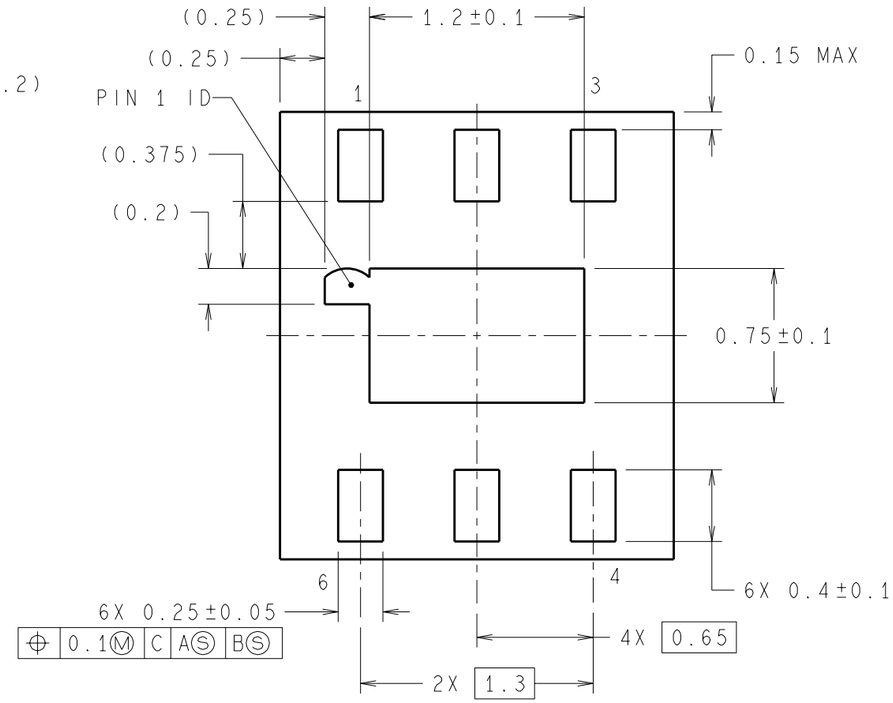


RECOMMENDED LAND PATTERN
1:1 RATIO WITH PKG SOLDER PADS

DIMENSIONS ARE IN MILLIMETERS







NOTES: UNLESS OTHERWISE SPECIFIED

1. STANDARD LEAD FINISH TO BE 5.08 MICROMETERS MINIMUM LEAD/TIN (SOLDER) ON COPPER.
2. THE PACKAGE IS SC70 LAND FOOTPRINT COMPATIBLE. IT IS NOT A PACKAGE SIZE COMPATIBLE TO SC70 5/6 LEAD.
3. NO JEDEC REGISTRATION AS OF MARCH 2002.

APPROVALS	DATE
DRAWN AFZNZAM S.	03/21/2002
DFTG. CHK. MARTA SUCHY	03/21/2002
ENGR. CHK. N.SANTHIRAN	03/21/2002

PROJECTION MM

National Semiconductor
2900 Semiconductor Dr, Santa Clara, CA 95052-8090

LLP, PLASTIC, DUAL,
2.2 X 2.5 X 0.75 mm BODY,
6 LD, 0.65mm PITCH, SC-70 LAND

SCALE	SIZE	DRAWING NUMBER	REV
NTS	B	(SC)MKT-LDB06A	A

FORMERLY: N/A

SHEET 1 of 1